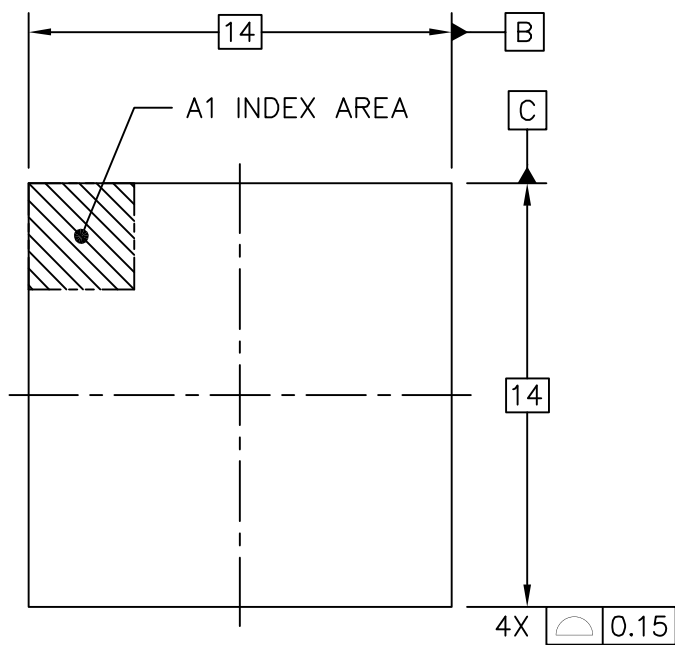
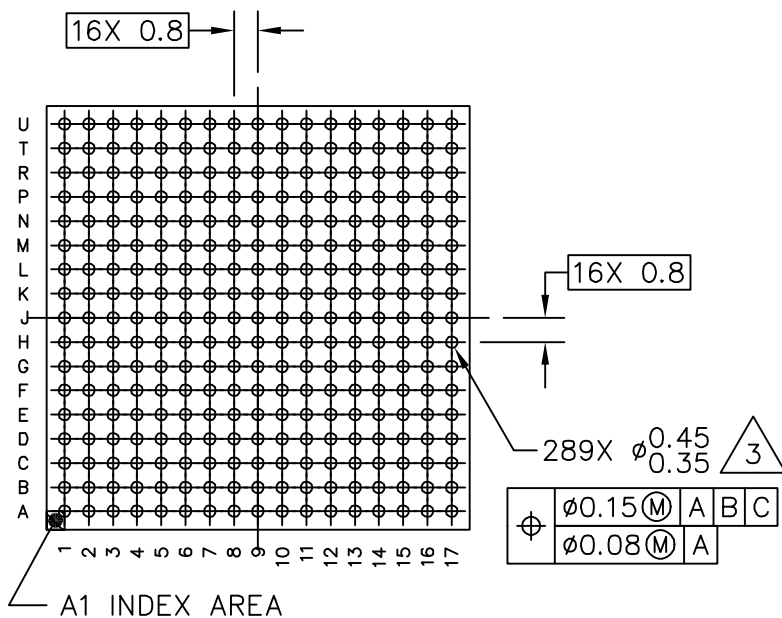
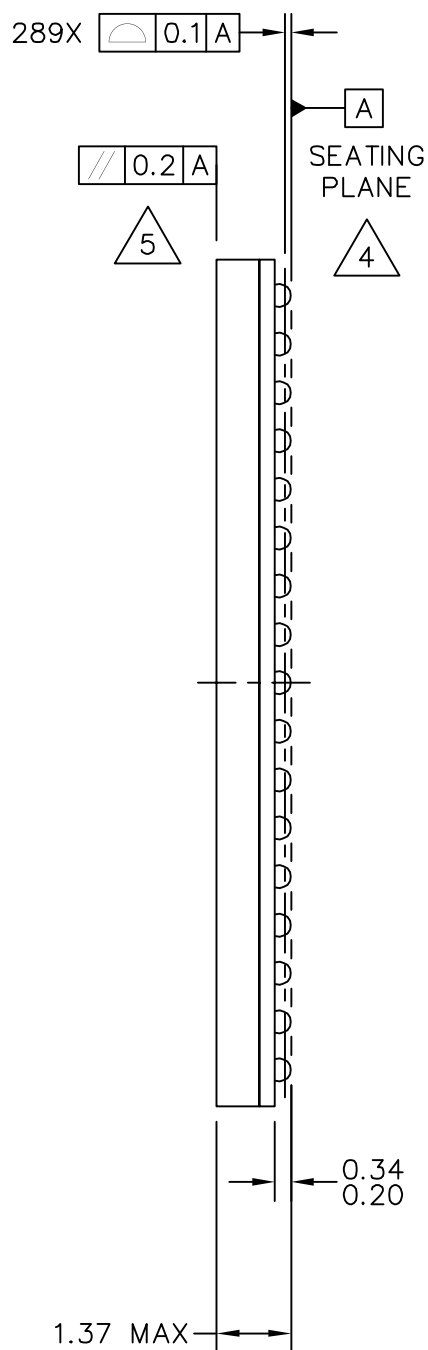




TOP VIEW



BOTTOM VIEW



SIDE VIEW

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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: PBGA, LOW PROFILE,
FINE PITCH, 289 I/O,
14 X 14 PKG, 0.8 MM PITCH (MAP)

DOCUMENT NO: 98ASA00101D

REV: 0

CASE NUMBER: 2092-01

20 NOV 2009

STANDARD: MO-275-JJAC-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

 4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: PBGA, LOW PROFILE, FINE PITCH, 289 I/O, 14 X 14 PKG, 0.8 MM PITCH (MAP)			DOCUMENT NO: 98ASA00101D		REV: 0
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